

VERSION OF AMENDED SECTION OF SPECIFICATION**WITH MARKINGS TO REFLECT CHANGES MADE**

The text to be deleted from the table as filed has been struck through. The text to be added to the table as filed is preceded and followed by the traditional double hyphens.

Attorney- Docket No. --Application Number--	Title of Application	First Named Inventor
45475-00015 --09/687,485--	Semiconductor Package Having Increased Solder Joint Strength	Kil Chin Lee
45475-00016 --09/687,487--	Clamp and Heat Block Assembly For Wire Bonding a Semiconductor Package Assembly	Young Suk Chung
45475-00018 --09/687,876--	Near Chip Size Semiconductor Package	Sean Timothy Crowley
45475-00020 --09/687,531--	Stackable Semiconductor Package and Method for Manufacturing Same	Sean Timothy Crowley
45475-00021 --09/687,530--	Stackable Semiconductor Package and Method for Manufacturing Same	Jun Young Yang
45475-00024 --09/687,126--	Method of and Apparatus for Manufacturing Semiconductor Packages	Hyung Ju Lee
45475-00028 --09/687,493--	Semiconductor Package Having Improved Adhesiveness and Ground Bonding	Sung Sik Jang
45475-00029 --09/687,541--	Semiconductor Package Leadframe Assembly and Method of Manufacture	Young Suk Chung

IN THE CLAIMS

A clean copy of all claims, as pending, are attached as Appendix A

Please amend the claims as follows:

1 1. (Amended) A semiconductor package, comprising:
2 a semiconductor chip provided with a plurality of input/output pads on its upper surface;
3 a chip paddle adjacent a bottom surface of [said] the semiconductor chip;
4 a plurality of internal leads surrounding [said] the chip paddle;
5 conductive wires for electrically connecting [said] the input/output pads of [said] the semiconductor
6 chip to [said] the internal leads; and
7 a package body comprised of encapsulation material that encapsulates [said] the semiconductor
8 chip, [said] the conductive wires, [said] the chip paddle and [said] the internal leads, wherein [said] the chip
9 paddle and [said] the internal leads are externally exposed at a bottom surface of [said] the chip paddle
10 and [said] the internal leads.

1 2. (Amended) The semiconductor package as set forth in claim 1, wherein:
2 a lower side area of [said] the chip paddle has an etched part wherein the etched part is about 10%
3 to about 90 % of [said] the lower side area of [said] the chip paddle, and [said] the etched part is located
4 inside [said] the package body.

1 3. (Amended) The semiconductor package as set forth in claim 2, wherein:

2 [said] the chip paddle and a lower surface[s] of [said] the internal leads are in a common plane,

3 and wherein [said] the chip paddle is thicker than [said] the internal leads.

1 4. (Amended) The semiconductor package as set forth in claim 1, wherein:

2 [said] the chip paddle and a lower surface[s] of [said] the internal leads are in a common plane,

3 and wherein [said] the chip paddle is thicker than [said] the internal leads.

1 5. (Amended) The semiconductor package as set forth in claim 1, wherein:

2 [said] the chip paddle is bonded to a bottom surface of [said] the semiconductor chip with an

3 adhesive.

1 6. (Amended) The semiconductor package as set forth in claim 1, wherein:

2 each of [said] the internal leads have an etched part at an end facing [said] the chip paddle.

1 7. (Amended) The semiconductor package as set forth in claim 1, wherein:

2 [said] the internal leads are externally exposed at their side surfaces and bottom surfaces.

1 13. (Amended) A packaged semiconductor, comprising:

2 a chip paddle adapted to receive a semiconductor chip;

3 a plurality of internal leads surrounding [said] the chip paddle wherein [said] the chip paddle and

4 [said] the leads comprise a leadframe; and

5 [said] the leadframe adapted to receive a package body comprised of encapsulation material for

6 encapsulating [said] the chip paddle and [said] the internal leads, wherein [said] the chip paddle and [said]

7 the internal leads are externally exposed at a bottom surface of [said] the chip paddle and [said] the internal

8 leads.

1 14. (Amended) The packaged semiconductor as set forth in claim 13, wherein:

2 a lower side area of [said] the chip paddle has an etched part wherein the etched part is about 10%

3 to about 90 % of [said] the lower side area of [said] the chip paddle, and [said] the etched part is located

4 inside [said] the package body.

1 15. (Amended) The packaged semiconductor as set forth in claim 14, wherein:

2 [said] the chip paddle and a lower surfaces of [said] the internal leads are in a common plane, and

3 wherein [said] the chip paddle is thicker than [said] the internal leads.

1 16. (Amended) The packaged semiconductor as set forth in claim 13, wherein:

2 [said] the chip paddle and a lower surfaces of [said] the internal leads are in a common plane, and

3 wherein [said] the chip paddle is thicker than [said] the internal leads.

- 1 17. (Amended) The packaged semiconductor as set forth in claim 13, wherein:
2 each of [said] the internal leads have an etched part at an end facing [said] the chip paddle.
- 1 18. (Amended) The packaged semiconductor as set forth in claim 13, wherein:
2 [said] the internal leads are externally exposed at their side surfaces and bottom surfaces.

REMARKS

Applicants request the Examiner to amend the application as requested above. The amendments made in the specification include replacing the column titled "Attorney Docket No." which identified U.S. patent applications by docket number with a column titled "Application Number" which identifies the same pending U.S. patent applications by serial number. At the time of filing the present application, the serial numbers of the applications identified in the table above were not available. Applicants have replaced each docket number of the table with the serial number of the application to which it corresponds.

Applicants request that the Examiner amend the specification as discussed and indicated herein. The amendment is to include serial numbers of patent applications which were filed on the same day as the present application, and were therefore unavailable at the time of filing this application. No new matter has been added.

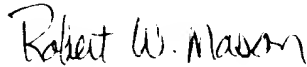
Additionally, Applicants respectfully request that the Examiner amend the claims in the manner indicated above. As discussed in the Response to Election/Restriction Requirement, filed herewith, Applicants have elected Group 1, Claims 1-7 and 13-18, responsive to the Office Action dated June 11, 2001. Claims 1-7 and 13-18 have been amended to attain consistent antecedent basis. Furthermore, Claims 3 and 4 have been amended to correct typographical errors, and Claims 19-25 have been added to broaden the scope of Applicants' invention. Applicants note that careful consideration has been made such that no new matter has been added.

The supplemental fee required for entry of this Preliminary Amendment is calculated in the Preliminary Amendment Transmittal Letter enclosed herewith. However, the Commissioner is hereby

Patent Application
Docket #45475-00019
99-58164

authorized to charge any additional amount required in connection therewith to deposit account number 10-0447 of Jenkins & Gilchrist, P.C.

Respectfully submitted,



Robert W. Mason
Reg. No.: 42,848

JENKENS & GILCHRIST, P.C.
1445 Ross Avenue, Suite 3200
Dallas, Texas 75202-2799
Telephone: 214-855-4500
Facsimile: 214-855-4300

:slf
Enclosure